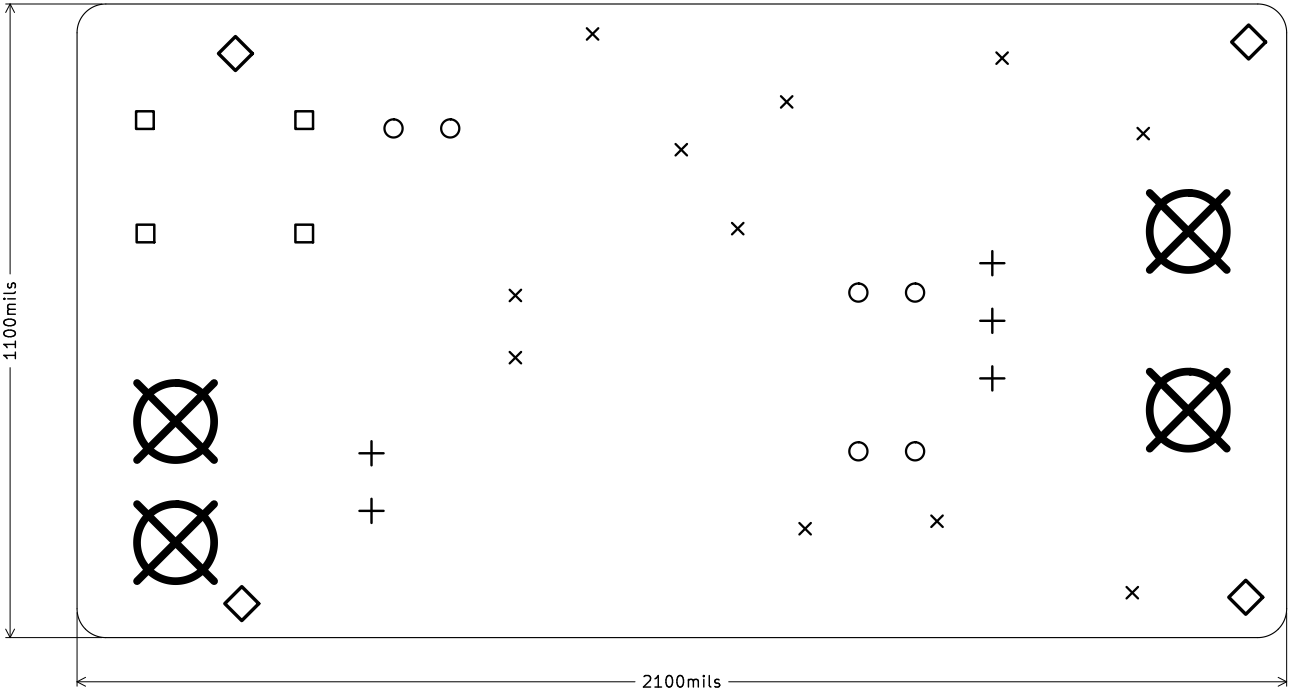


BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	62.99 mils
Board overall dimensions:	2100.00 mils x 1100.00 mils		
Min track/spacing:	10.00 mils / 10.00 mils	Min hole diameter:	19.69 mils
Copper Finish:	HAL SnPb	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

Drill Map:
x 0.508mm / 0.0200" (11 holes)
o 0.800mm / 0.0315" (6 holes)
+ 1.067mm / 0.0420" (5 holes)
□ 1.100mm / 0.0433" (4 holes)
◇ 1.500mm / 0.0591" (4 holes) (not plated)
⊗ 3.400mm / 0.1339" (4 holes) (not plated)



1868 SPACE COOKIES

Sheet: File: BeamBreak-v1.kicad_pcb		
Title: Beam Break Adapter		
Size: B	Date: 2026-01-02	Rev: 1
KiCad E.D.A. 9.0.7		Id: 1/1